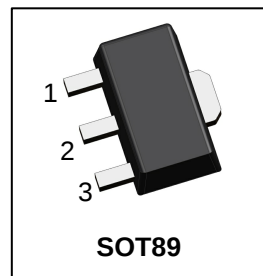


LBSS5250Y3T1G

Midium Power PNP Transistors

1. FEATURES

- Low saturation voltage, typically
- High speed switching
- We declare that the material of product compliance with RoHS requirements and Halogen Free.

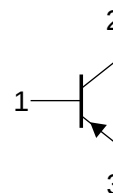


2.APPLICATIONS

- Driver

3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LBSS5250Y3T1G	H	5000/Tape&Reel



4. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Collector–Emitter Voltage	VCEO	-50	V
Collector–Base Voltage	VCBO	-50	V
Emitter–Base Voltage	VEBO	-6	V
Collector Current	IC	-2	A
Collector Current(Pulse)	ICP	-4	A

5. THERMAL CHARACTERISTICS

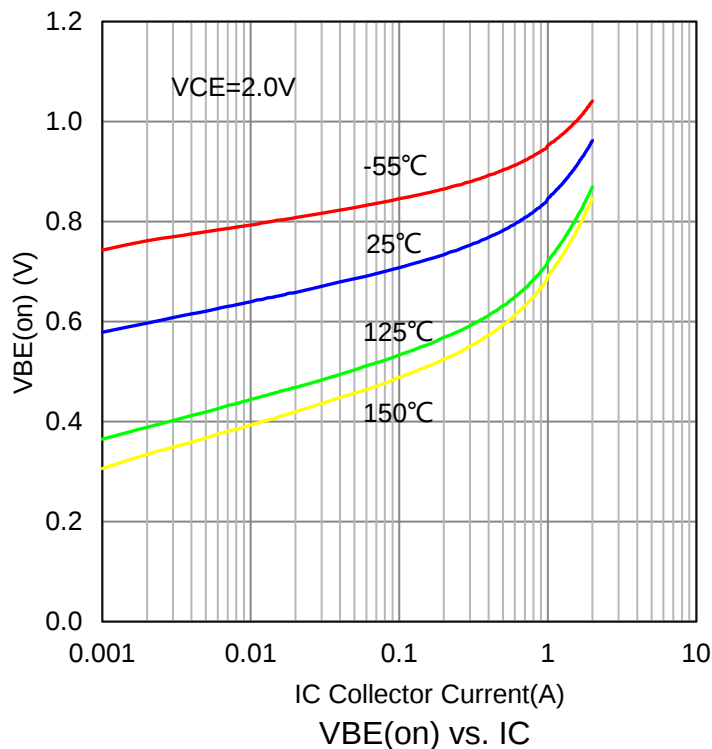
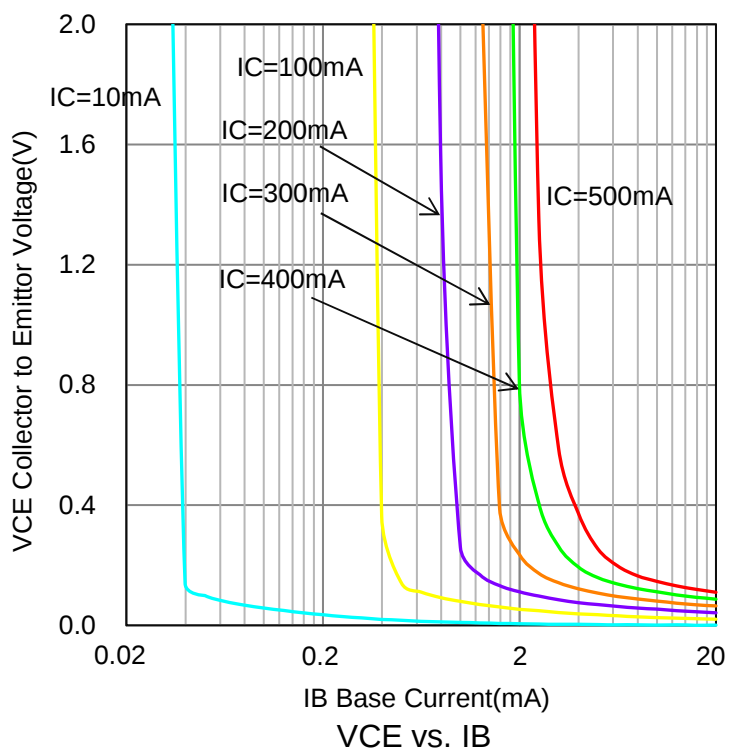
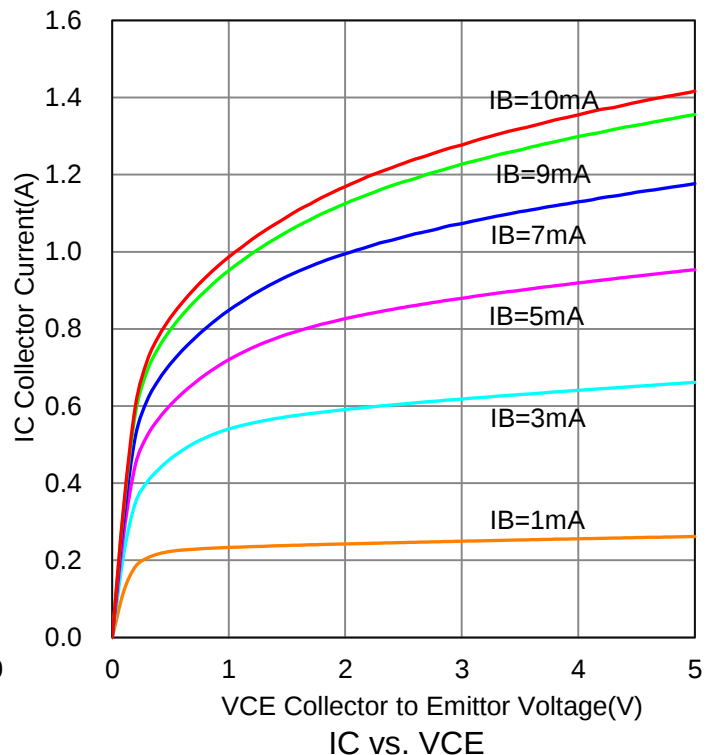
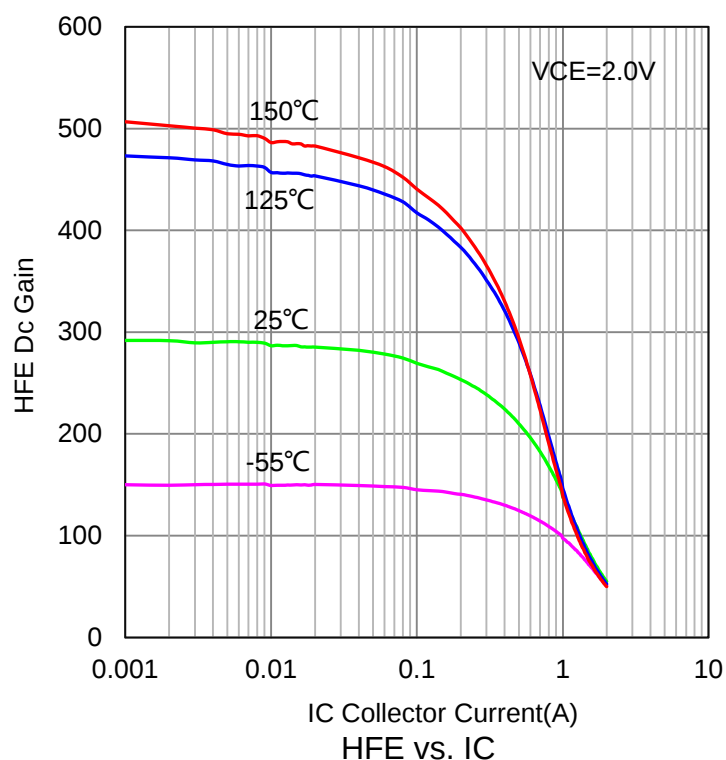
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	550 4.4	mW mW/°C
Thermal Resistance, Junction–to–Ambient	RθJA	225	°C/W
Junction and Storage temperature	TJ,Tstg	-55~+150	°C

1.PCB Size:30.0mm×25.0mm×1.6mm,FR-4 Board;

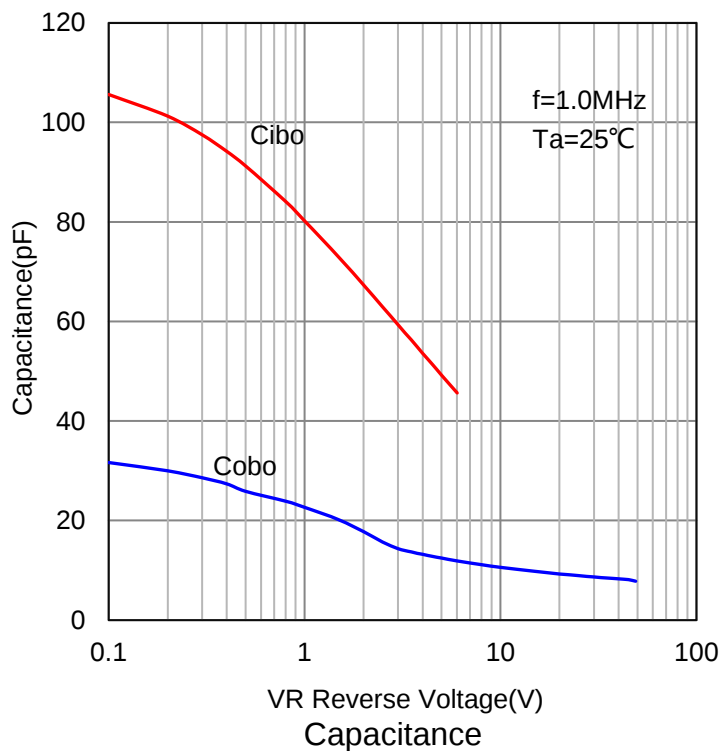
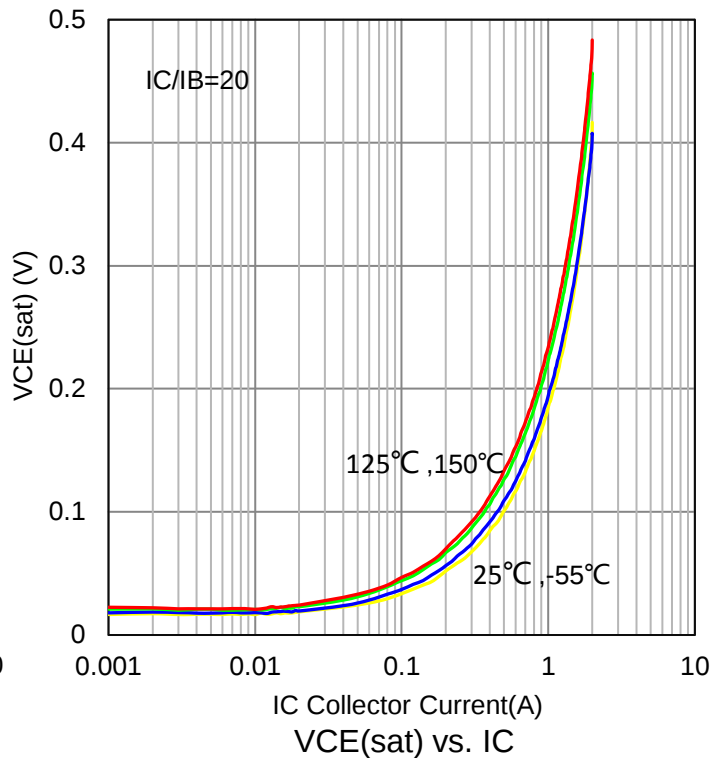
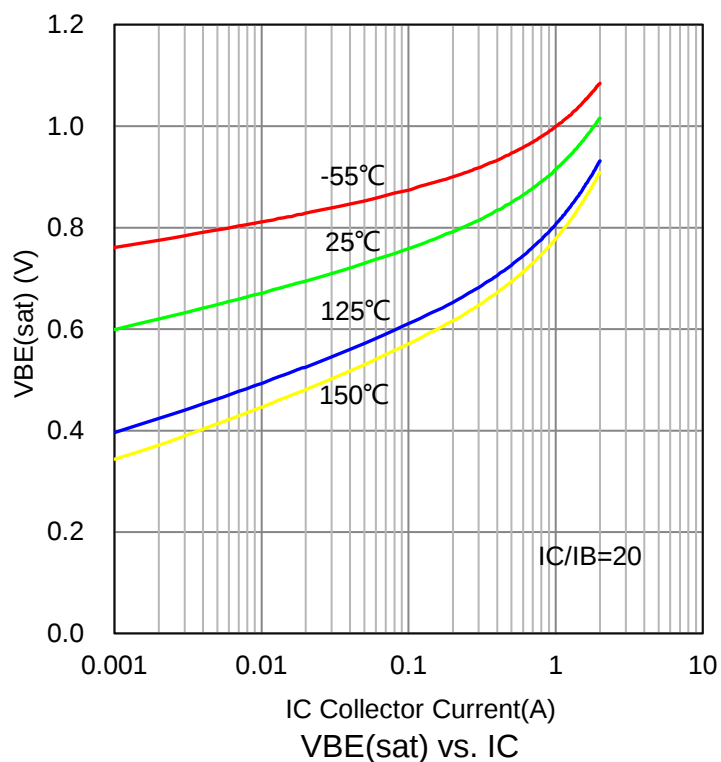
6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Collector-emitter breakdown voltage (IC = -1mA)	BVCEO	-50	-	-	V
Collector-base breakdown voltage (IC = -100μA)	BVCBO	-50	-	-	V
Emitter-base breakdown voltage (IE = -100μA)	BVEBO	-6	-	-	V
Collector Cutoff Current (VCB = -50V, IE = 0)	ICBO	-	-	-1	μA
Emitter Cut-off Current (VEB = -4V, IC = 0)	IEBO	-	-	-1	μA
Collector-Emitter cutoff Current (VCE = -50V, IB=0)	ICEO	-	-	-10	μA
DC Current Gain (VCE = -2V, IC = -50mA)	HFE	180	-	450	
Collector–Emitter Saturation Voltage (IC = -700mA, IB = -35mA)	VCE(sat)	-	-200	-400	mV
Transition Frequency(Note 1) (VCE = -10V, IE = 300mA, f=100MHz)	fT	-	320	-	MHz
Collector Output Capacitance (VCB = -10V, IE = 0A, f=1MHz)	Cob	-	22	-	pF

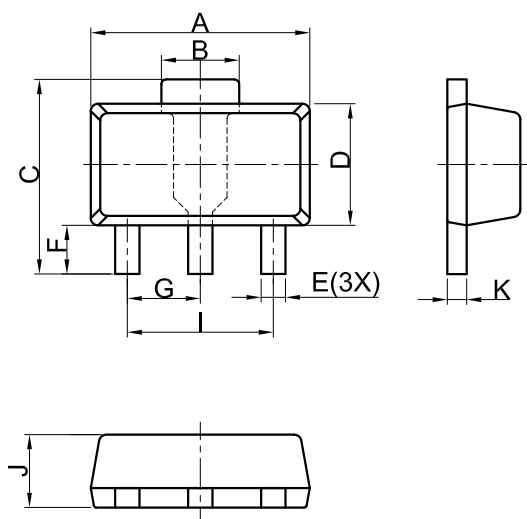
7. ELECTRICAL CHARACTERISTICS CURVES



7.ELECTRICAL CHARACTERISTICS CURVES(Con.)



8.OUTLINE AND DIMENSIONS

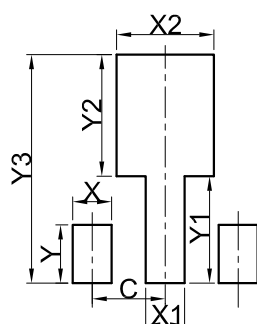


SOT89			
DIM	MIN	NOR	MAX
A	4.30	4.50	4.70
B	1.40	1.60	1.80
C	3.90	4.00	4.25
D	2.30	2.50	2.70
E	0.40	0.50	0.58
F	0.90	1.00	1.20
G	1.50 BSC		
I	3.00 BSC		
J	1.40	1.50	1.60
K	0.34	0.40	0.50
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish $Ra0.4\pm0.2\mu m$
2. Bottom package surface finish $Ra0.7\pm0.2\mu m$
3. Side package surface finish $Ra0.4\pm0.2\mu m$
4. Protrusion or Gate Burrs shall not exceed 0.10mm per side.

9.SOLDERING FOOTPRINT



SOT89	
DIM	(mm)
X	0.80
Y	1.20
X1	0.80
Y1	2.20
X2	2.00
Y2	2.50
C	1.50
Y3	4.70

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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